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(54) SURFACE TENSION DRIVEN FLEXIBLE **ELECTRONICS TRANSFER PRINTING METHOD**

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(57)**ABSTRACT**

The present invention discloses a surface tension driven flexible electronics transfer printing method which uses a surfactant liquid membrane or a surfactant bubble as a transfer printing stamp, to realize the transfer printing of an electronic device with nanometer/micron/submillimeter thickness. A process of transfer printing is transparent and visible in a "what you see is what you get" manner to realize the accurate positioning of the electronic device. A local load technology is introduced, which is suitable for arbitrary complex curved substrate to realize diverse transfer printing. The electronic device can be transfer-printed to an application substrate with extremely-low interfacial adhesion, without the requirement for the strong and weak adhesion switching strategy of the traditional transfer printing. An unbearable electronic device membrane can be transferprinted to an fragile receiving substrate with no loss or low loss, without the introduction of pre-pressure.

